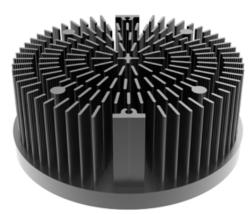


PADLED Heat Sink

Wakefield- Vette's PADLED is designed with 99.7% high-purity aluminum cold forging process. The design of the series is simple and gorgeous, and the blade is rectangular in a radial patern, which makes the convection heat dissipation reasonable. This heat sink also has 4 PCS holes on top. This is compatible with Light Modules such as Edison, Xicato, Bridgelux, Osram, Lumileds, Cree, Tridonic, LG, Lustrous, Prolight, Samsung, SHARP, Luminus and Philips.



Features:

- Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages
- Side fins to be frilled M3 or M4 Hotles
- Several Diameters, Several Standard heights
- Forged from highly conductive aluminum
- Black Anodized
- Blank surface with no holes to mount any device listed below

Compatible with:

- Bridelux: Vero 18/22 Vero SE 18/29 LED engines;
- Cree: XLamp CXA 25xx, Xlamp CXB 25xx, CXA 30xx, Xlamp CXB 30xx LED en
- Citizen: CLU036, CLU038, CLU721, CLU711, CLU046, CLU048, CLU731 LED engines;
- Edison: EdiLex III COB LED engines;
- GE lighting: InfusionTM LED engines;
- LG Innotek: 32W, 42W, 56W LED engines;
- LumiLEDS: LUXEON 1211, LUXEON 1216, LUXEON 1812, LUXEON 1825 LED eng
- Lumens: Ergon-COB-2530, 2540, 3050, 3070 LED engines;
- Luminus: CXM-18, CLM-22, CXM-22 LED engines;
- Nichia: NFCWL036B, NFCLL036B, NFCWL060B, NFCLL060B LED engines;
- Osram: SOLERIQ® S 19, Core series LED engines;
- Philips: Fortimo SLM LED engines;
- Prolight Opto: PABS, PABA, PACB, PANA LED engines;
- Samsung: LC026B, LC033B, LC040B, LC040D, LC060D, LC080D LED engines;
- Seoul Semiconductor: Acrich MJT COBs, DC COB LED engines;
- Tridonic: SLE G6 19mm, SLE G6 23mm LED engines;
- Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;
- Xicato: XSM, XIM, XTM LED engines;

WAKEFIELDTHERMAL

PADED Heat Sink

130mm Diameter

WKV	/ Part		Height	Diameter	Max. Lumen	Dissipated Power	Thermal Resistance (
Nun	nber	Description	(mm)	(mm)	(lm)	(W)	°C/W)	Weight (g)
PADLED	D-13080	PAD LED Heat Sink 130MM DIA 80H	80	130	4600	33	1.5	492
PADLED	-130100	PAD LED Heat Sink 130MM DIA 100H	100	130	6700	48	1	625

*Note: All Bases Have no Holes

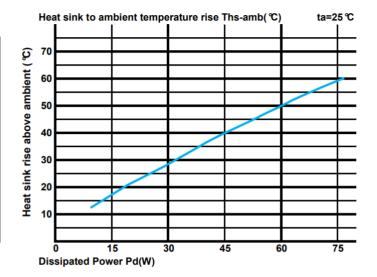






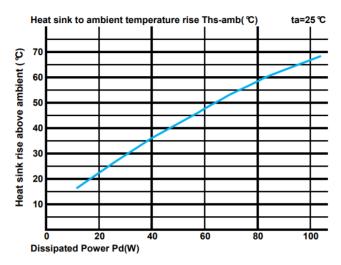
Thermal Data PADLED-13080

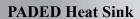
	Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature riseThs-amb (℃)	
	Dissipated Power Pd(W)	15.0	1.13	17.0	
		30.0	0.93	28.0	
		45.0	0.89	40.0	
		60.0	0.83	50.0	
	Dis	75.0	0.77	58.0	



Thermal Data PADLED-130100

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (℃)	
W)	20.0	1.10	22.0	
Dissipated Power Pd(W)	40.0	0.90	36.0	
	60.0	0.78	47.0	
	80.0	0.73	58.0	
	100.0	0.66	66.0	







165mm Diameter

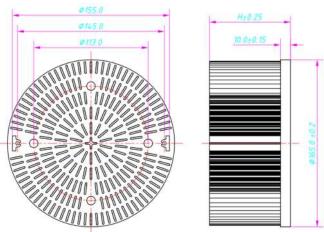
						Thermal Resistance (
WKV Part Number	Description	Height (mm)	Diameter (mm)	Max. Lumen (lm)	Dissipated Power (W)	°C/W)	Weight (g)
PADLED-16580	PAD LED Heat Sink 165MM DIA 80H	80	165	15000	95	0.52	1550
PADLED-165100	PAD LED Heat Sink 165MM DIA 100H	100	165	16800	120	0.4	1700

*Note: All Bases Have no Holes



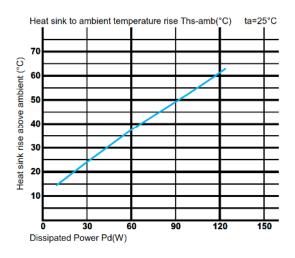






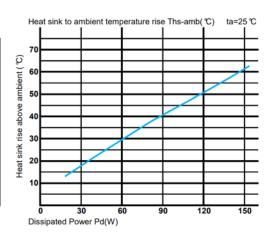
Thermal Data PADLED-16580

_				
		= Pe x -ηL)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (*C)
l	۷)	30.0	0.78	23.5
I	Dissipated Power Pd(W)	60.0	0.63	38.0
I		90.0	0.52	47.0
I		120.0	0.51	61.0
	Ö	150.0	0.49	73.0



Thermal Data PADLED-165100

	= Pe x -ηL)	Heat sink to ambient thermal resistance Rhs-amb (*C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
S	30.0	0.60	18.0	
er Pd(V	60.0	0.48	29.0	
Dissipated Power Pd(W)	90.0	0.44	40.0	
ssipate	120.0	0.42	50.0	
ä	150.0	0.41	61.0	





PADED Heat Sink

225mm Diameter

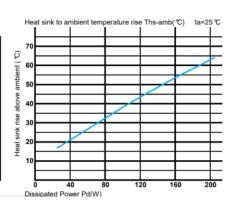
						Thermal	
WKV Part		Height	Diameter			Resistance	
Number	Description	(mm)	(mm)	Max. Lumen (lm)	Dissipated Power (W)	(°C/W)	Weight (g)
PADLED-22560	PAD LED Heat Sink 225MM DIA 60H	60	225	21000	150	0.3	2220
PADLED-225100	PAD LED Heat Sink 225MM DIA 100H	100	225	28000	200	0.2	3150

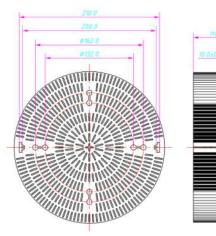
*Note: All Bases Have no Holes



Thermal Data PADLED-22560

_			
Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (*C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
۷)	40.0	0.53	21.0
er Pd(V	80.0	0.41	33.0
d Powe	120.0	0.37	44.0
Dissipated Power Pd(W)	160.0	0.33	53.0
Di	200.0	0.32	63.0

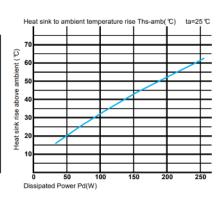


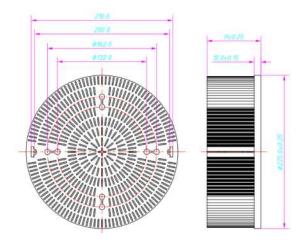




Thermal Data PADLED-225100

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance . Rhs-amb (*C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
S	50.0	0.40	20.0
er Pd(V	100.0	0.32	32.0
Dissipated Power Pd(W)	150.0	0.29	43.0
ssipate	200.0	0.26	52.0
ā	250.0	0.24	61.0





Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Wakefield Thermal:

PADLED-165100 PADLED-225100 PADLED-130100 PADLED-16580 PADLED-13080 PADLED-22560